



SPECIFICATION FOR APPROVAL

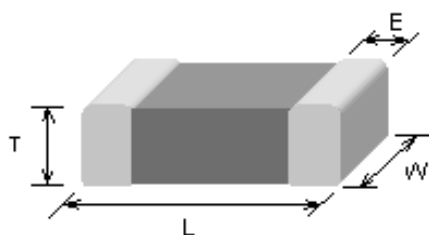
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PRODUCT DETAIL

Electrical Characteristics			Test Instruments
Z	Ω (See Page 7~8)	TEST FREQ: MHz (See Page 7~8)	•HP4291B RF IMPEDANCE / MATERIAL ANALYZER •HP4338A/B MILLIOHMMETER •Agilent 8720ES S-PARAMETER NETWORK ANALYZER •HP6632B SYSTEM DC POWER SUPPLY
DCR	Ω (See Page 7~8)		
IDC	mA (See Page 7~8)	TEST LEVEL: 250 mV	

SHAPES AND DIMENSIONS



Unit: mm

TYPE	100505 (EIA 0402)	160808 (EIA 0603)	201209 (EIA0805)	321611 (EIA1206)	322513 (EIA1210)	451616 (EIA1806)	453215 (EIA1812)
L	1.0±0.10	1.6±0.15	2.0±0.20	3.2±0.20	3.2±0.20	4.5±0.25	4.5±0.25
W	0.5±0.10	0.8±0.15	1.25±0.2	1.6±0.20	2.5±0.20	1.6±0.20	3.2±0.25
T	0.5±0.10	0.8±0.15	0.9±0.20	1.1±0.20	1.3±0.20	1.6±0.20	1.5±0.25
E	0.25±0.1	0.3±0.20	0.5±0.30	0.5±0.30	0.5±0.30	0.6±0.40	0.6±0.40

PART NUMBER CODE

MHC 1608 S 12 1 P A
1 2 3 4 5 6 7

- Series Name
- Size Code : the first two digitals : length(mm), the last two digitals : width(mm)
- Material Code
- Impedance(Ω) + 25% } (ex : 900=90 Ω ; 121=120 Ω)
- Fixed Decimal Point
- Rated Current

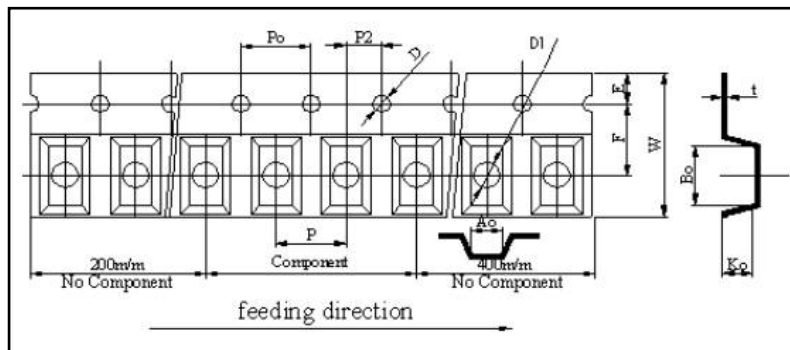
Code

L=1000mA	M=1500mA	N=2000mA	P=2500mA
Q=3000mA	R=4000mA	U=5000mA	W=6000mA

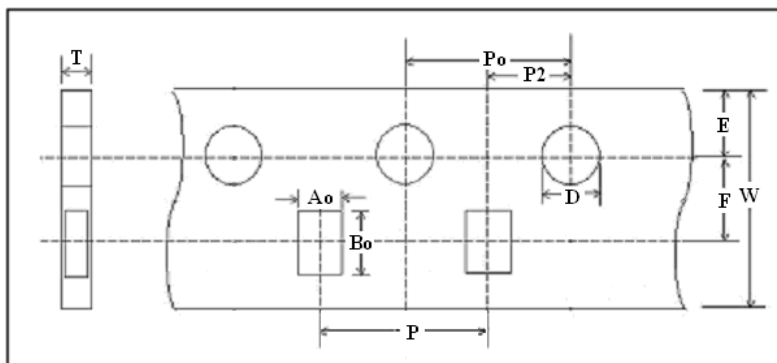
- Soldering : Green Parts : A—Lead-Free

TAPE AND REEL SPECIFICATIONS

PLASTIC CARRIER



PAPER CARRIER

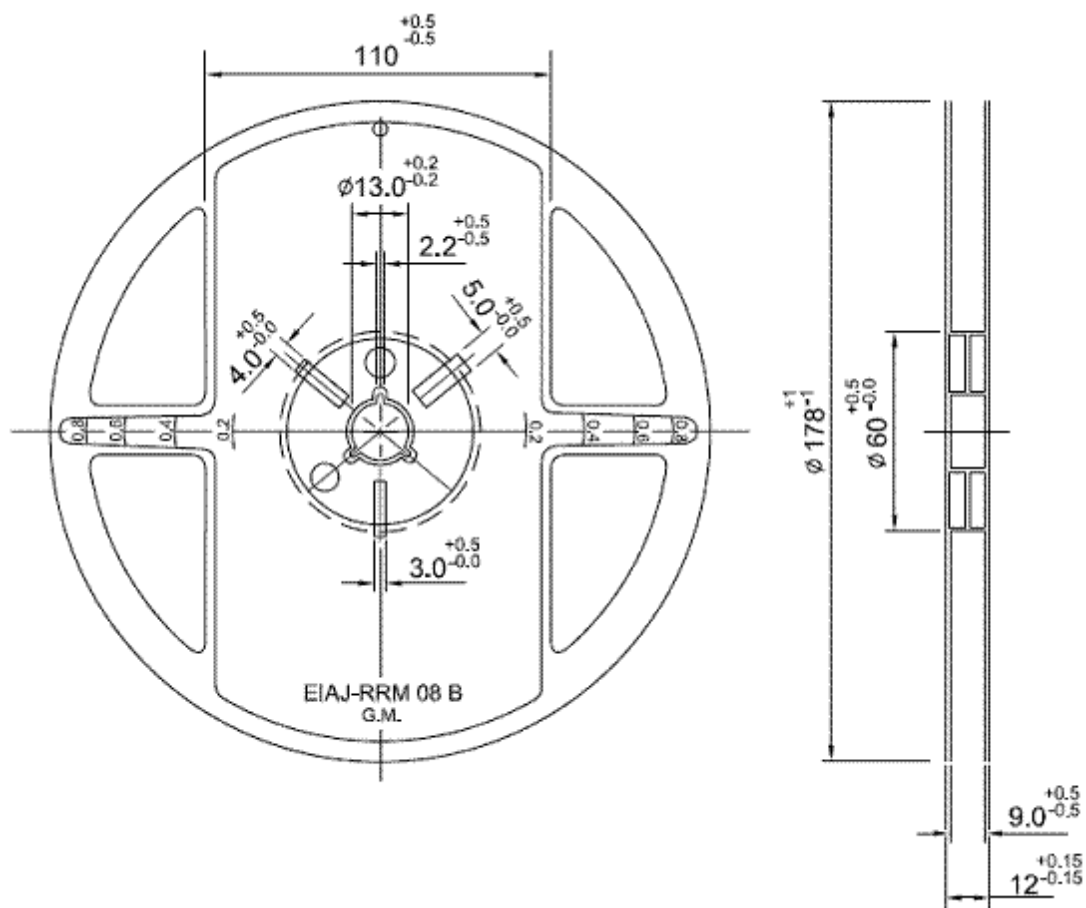


TAPING DIMENSIONS

Unit: mm

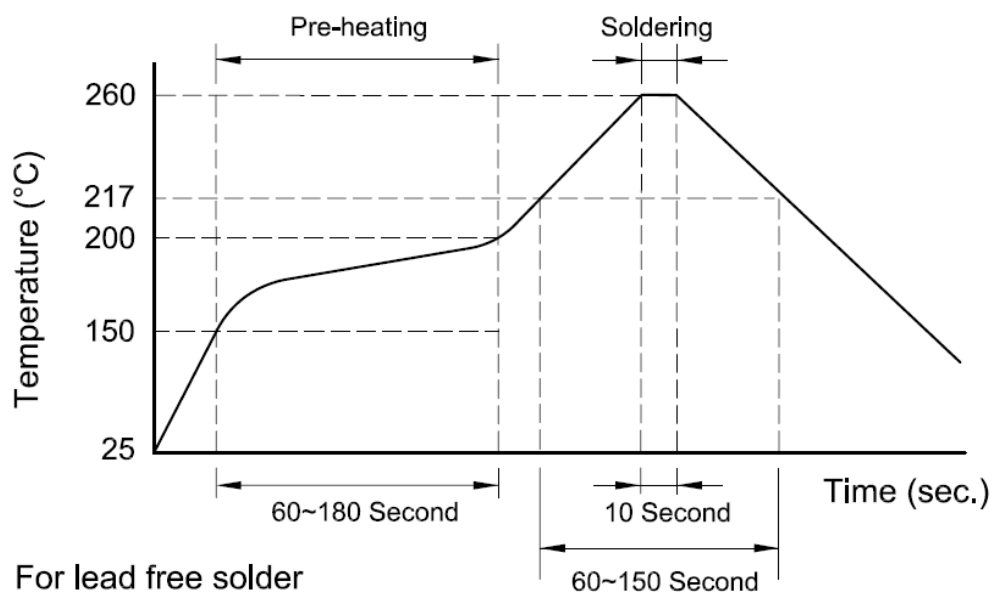
	453215	451616	322513	321611	201212	201209	201209	160808	100505
Symbol	PLASTIC	PLASTIC	PLASTIC	PLASTIC	PLASTIC	PLASTIC	PAPER	PAPER	PAPER
W	12 ±0.1	11.7~12.3	7.7~8.3	7.9~8.3	7.9~8.3	7.9~8.3	8.0 ±0.1	8.0 ±0.1	8.0 ±0.1
P	8.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	2.0 ±0.05
E	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.10	1.75 ±0.05
F	5.5 ±0.05	5.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.1	3.5 ±0.1	3.5 ±0.05
D	1.55 ±0.05	1.55 ±0.05	1.55 ±0.05	1.55 ±0.05	1.50 ±0.05	1.50 ±0.10	1.56 ±0.10	1.56 ±0.10	1.55 ±0.05
D1	1.5~1.75	1.5~1.75	0.95~1.20	0.95~1.20	0.95~1.20	1.0~1.25	NA	NA	NA
P ₀	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1	4.0 ±0.1
P ₁₀	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	NA	NA
P ₂	2.0 ±0.05	2.0 ±0.05	2.0 ±0.05	2.0 ±0.05	2.0 ±0.05	2.0 ±0.05	2.0 ±0.1	2.0 ±0.1	2.0 ±0.05
A ₀	3.66 ±0.1	1.83 ±0.1	2.57 ±0.1	1.85 ±0.1	1.42 ±0.1	1.42 ±0.1	1.50 ±0.05	1.05 ±0.05	0.62 ±0.03
B ₀	4.95 ±0.1	4.85 ±0.1	3.4 ±0.1	3.43 ±0.1	2.26 ±0.1	2.24 ±0.1	2.30 ±0.05	1.85 ±0.05	1.12 ±0.03
K ₀ (T)	1.83 ±0.1	1.83 ±0.1	1.32 ±0.1	1.22 ±0.1	1.30 ±0.1	1.04 ±0.10	0.95 ±0.05	0.95 ±0.05	0.60 ±0.03
t	0.23 ±0.1	0.29 ±0.1	0.25 ±0.1	0.25 ±0.1	0.23 ±0.1	0.25 ±0.1	NA	NA	NA

Unit: mm

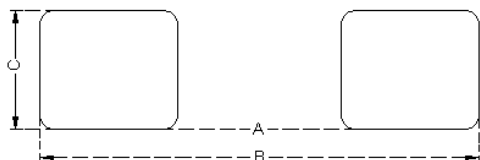


Reel Packaging Quantity									
PART SIZE (EIA SIZE)		1005 (0402)	1608 (0603)	201209 (0805)	201212 (0805)	3216 (1206)	3225 (1210)	4516 (1806)	4532 (1812)
7" REEL	Qty. (pcs)	10,000	4,000	4,000	3,000	3,000	2,000	2,000	1,000

RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING



SOLDER LAND INFORMATION

Unit: mm (inches)

Size	A	B	C
1005	0.4 ~ 0.6 (0.015 ~ 0.023)	1.6 ~ 2.6 (0.063 ~ 0.102)	0.4 ~ 0.7 (0.016 ~ 0.027)
1608	0.5 ~ 0.7 (0.019 ~ 0.027)	2.1 ~ 3.1 (0.083 ~ 0.122)	0.65 ~ 0.95 (0.026 ~ 0.037)
2012	1.0 ~ 1.2 (0.039 ~ 0.047)	3.0 ~ 4.0 (0.118 ~ 0.157)	0.8 ~ 1.1 (0.031 ~ 0.043)
3216	2.0 ~ 2.4 (0.079 ~ 0.094)	4.2 ~ 5.2 (0.165 ~ 0.204)	1.0 ~ 1.4 (0.039 ~ 0.055)
3225	2.1 ~ 2.3 (0.082 ~ 0.090)	4.2 ~ 5.2 (0.165 ~ 0.204)	2.2 ~ 2.5 (0.086 ~ 0.098)
4516	3.4 ~ 3.7 (0.133 ~ 0.145)	6.3 ~ 7.3 (0.248 ~ 0.287)	1.3 ~ 1.7 (0.051 ~ 0.067)
4532	3.4 ~ 3.7 (0.133 ~ 0.145)	6.3 ~ 7.3 (0.248 ~ 0.287)	2.9 ~ 3.2 (0.144 ~ 0.126)



RELIABILITY AND TEST CONDITION

Stress	Performance	Test Condition
Resistance to Solder Heat	The chip should not crack; More than 90% of the terminal electrode should be covered with solder, free from defects, chip body should not expose.	1. Solder: SHEN MAU (Sn60A-B20) 2.Solder Temp: 265 ±5°C 3.Flux: Rosin 4.Dip time: 10 ±1 sec
Solder ability 1 (IR Re-flow test)	1.Sn cover area need to over half thickness of chip 2.Chip shift distance under 50% of width 3.No short, open,...etc defect symptom	For Lead Process 1.Solder: Alpha (63Sn/37Pb) 2.General:135/135/195/235°C For Lead-free Process 1.Solder: Alpha (SAC305) 2.100%TIN:155/155/220/250°C 3.Sn:Ag:Cu=96.5:3:0.5
Solder ability 2 (After steam 8 hrs)	More than 90% of the terminal electrode should be covered with new solder	1.Steam 8 hrs 2.Solder: SHEN MAU (Sn60A-B20) 3.Solder Temp.:235 ±5°C 4.Flux: Rosin 5.Dip time:5 ±1 sec
Terminal Strength	The terminal electrode should not peel off	100505>0.2kgt, 160808>0.3kgt, 201209>0.6kgt, 201212>0.6kgt, 321611>1.0kgt, 322513>1.0kgt, 451616>1.0kgt, 453215>1.5kgt, ; pulling time:30 ±5 sec
Bending Strength	The body should not be damaged by force applied on the right	100505>0.2kgf, 160808>0.3kgf, 201209>1.0kgf, 201212>1.0kgf, 321611>2.0kgf, 322513>2.5kgf, 451616>2.5kgf, 453215>2.5kgf,
Flexure Strength	No mechanical damage shall be noticed even when the board is bent 2 mm (0.079 inches)	1. At ambient temperature & Humidity 2.To bend 2 mm
Thermal Shock (Temperature Cycle)	1. No mechanical damage 2. Inductance should be within ±10% of the initial value 3.Q value should be within ±30% of the initial value 4.Impedance value should be within ±20% of the initial value	1. Temperature:-40 ~ 85°C For 30 minutes each 2. Cycle: 100 cycles 3. Measurement: At ambient temperature 24 hours after test completion



Stress	Performance	Test Condition
Operational Life	1.No mechanical damage 2.Inductance should be within $\pm 10\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value	1. Temperature: $125 \pm 5^{\circ}\text{C}$ 2. Testing time: 1000 hrs 3. Applied current: Full rated current 4. Measurement: At ambient temperature 24 hours after test completion
Biased Humidity	1.No mechanical damage 2.Inductance should be within $\pm 10\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value	1.Temperature: 40°C 2.Humidity: 90-95 % RH 3. Applied current: Full rated current 4. Testing time: 1000 hrs 5. Measurement: At ambient temperature 24 hours after test completion
Rated Current	1. MCB / MFI / MCI product Surface temperature below room temperature plus 10°C 2. MHC product surface temp. below room temperature plus 40°C	1. At ambient temperature & humidity 2. Testing time: 5 minutes (under full rated current)

GENERAL TECHNICAL DATA

Operating temperature range : $-55^{\circ}\text{C} \sim +125^{\circ}\text{C}$

Storage temperature (on board): $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

Storage Condition : Less than 40°C and 70% RH

Storage Time: 12 months max.

Soldering method: Reflow or Wave Solderin



PRODUCT DETAILS

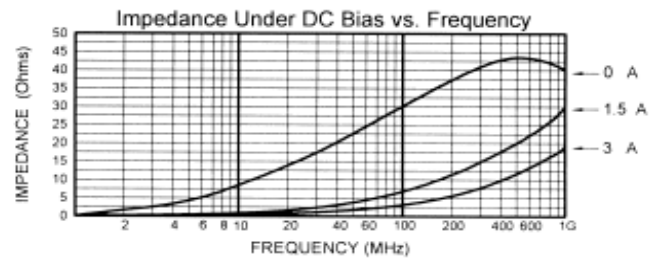
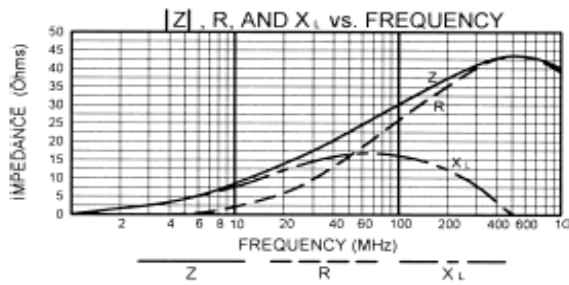
Part No.	Impedance(Ω) +/-25%	Test Freq.(MHz)	DCR(Ω) (max)	Rated Current (mA)
MHC1005 Series				
MHC1005S100NA	10	100	0.09	2000
MHC1005S300NA	30	100	0.09	2000
MHC1005S600LA	60	100	0.20	1000
MHC1005S121LA	120	100	0.20	1000
MHC1608 Series				
MHC1608S300QA	30	100	0.04	3000
MHC1608S600QA	60	100	0.04	3000
MHC1608S800QA	80	100	0.04	3000
MHC1608S121PA	120	100	0.07	2500
MHC1608S221NA	220	100	0.09	2000
MHC1608S301NA	300	100	0.09	2000
MHC1608S451MA	450	100	0.15	1500
MHC1608S601LA	600	100	0.20	1000
MHC2012 Series				
MHC2012S110WA	11	100	0.015	6000
MHC2012S260NA	26	100	0.09	2000
MHC2012S310WA	31	100	0.015	6000
MHC2012S400RA	40	100	0.03	4000
MHC2012S600QA	60	100	0.04	3000
MHC2012S800UA	80	100	0.02	5000
MHC2012S900UA	90	100	0.02	5000
MHC2012S121UA	120	100	0.02	5000
MHC2012S221QA	220	100	0.04	3000
MHC2012S251QA	250	100	0.04	3000
MHC2012S301NA	300	100	0.09	2000
MHC2012S331NA	330	100	0.09	2000
MHC2012S601NA	600	100	0.09	2000
MHC3216 Series				
MHC3216S500WA	50	100	0.015	6000
MHC3216S600QA	60	100	0.04	3000
MHC3216S750QA	75	100	0.04	3000
MHC3216S800RA	80	100	0.03	4000
MHC3216S900QA	90	100	0.04	3000
MHC3216S121WA	120	100	0.015	6000
MHC3216S151NA	150	100	0.09	2000
MHC3216S501PA	500	100	0.07	2500
MHC3216S601PA	600	100	0.07	2500
MHC3216S122LA	1200	100	0.20	1000
MHC3225 Series				
MHC3225S600MA	60	100	0.15	1500
MHC3225S102NA	1000	50	0.09	2000



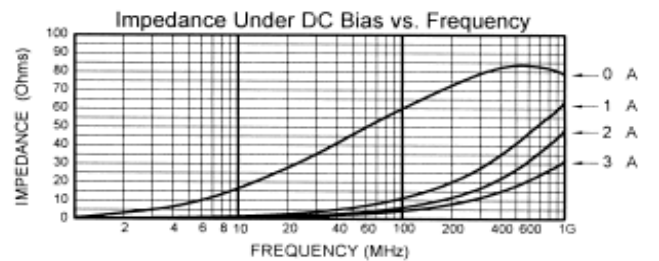
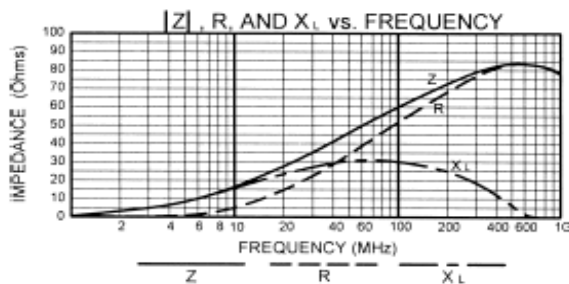
Part No.	Impedance(Ω) +/-25%	Test Freq.(MHz)	DCR(Ω) (max)	Rated Current (mA)
MHC4516 series				
MHC4516S600WA	60	100	0.015	6000
MHC4516S800WA	80	100	0.015	6000
MHC4516S471NA	470	100	0.09	2000
MHC4516S851MA	850	100	0.15	1500
MHC4532 series				
MHC4532S800WA	80	100	0.015	6000
MHC4532S121WA	120	100	0.015	6000
MHC4532S151WA	150	100	0.015	6000
MHC4532S601QA	600	50	0.04	3000
MHC4532S681QA	680	50	0.04	3000
MHC4532S132QA	1300	60	0.04	3000

PRINT

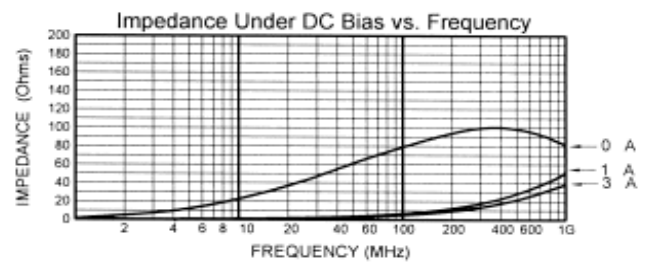
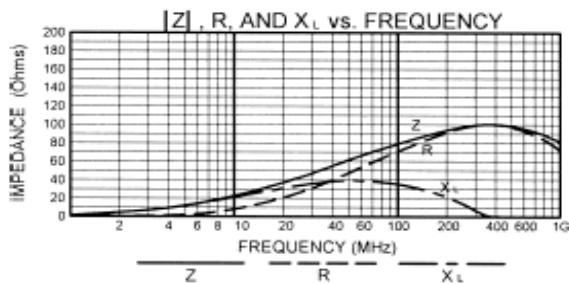
MHC1608S300Q



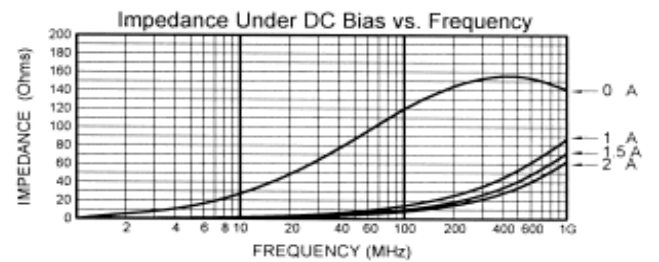
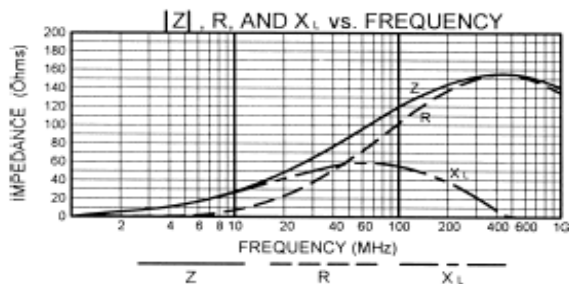
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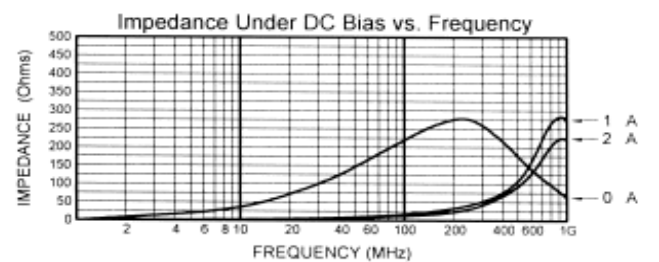
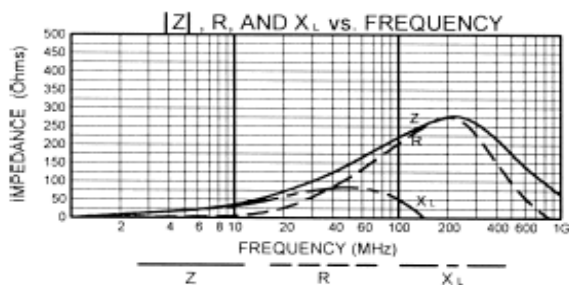
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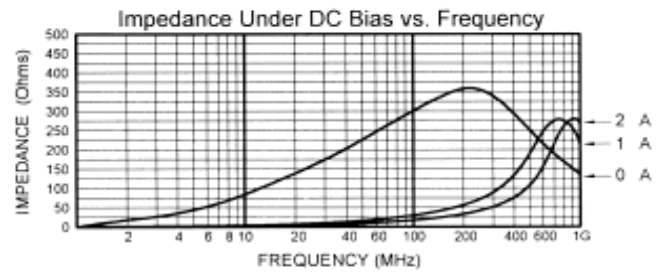
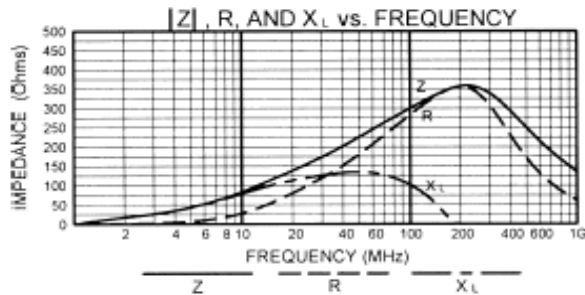
MHC1608S121N



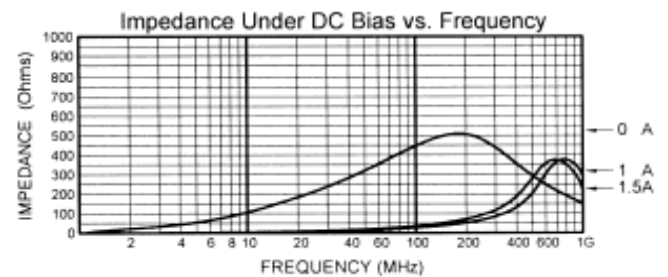
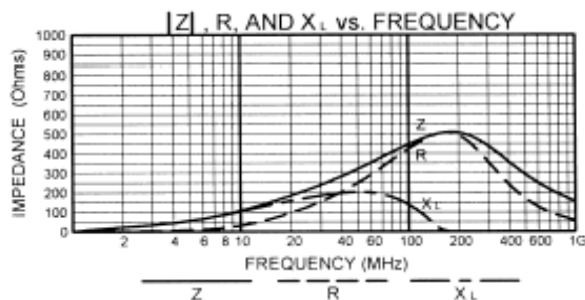
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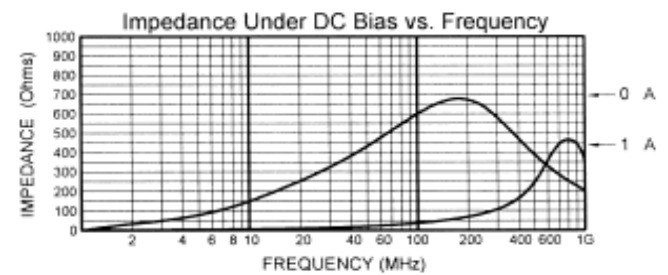
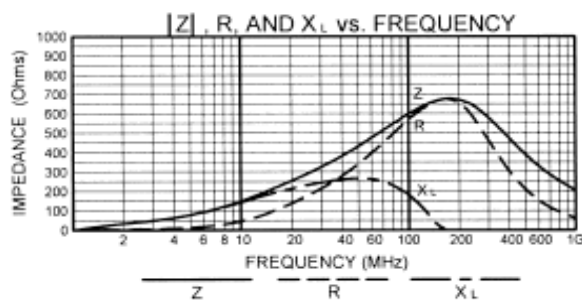
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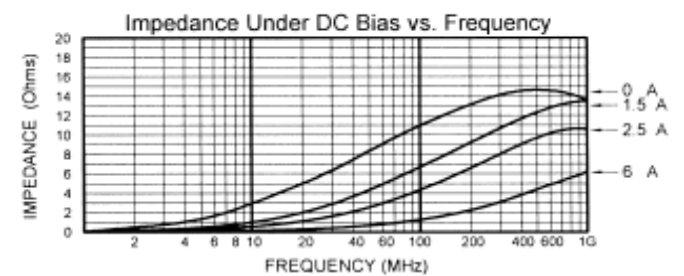
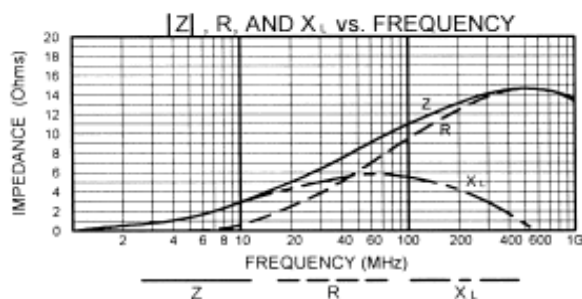
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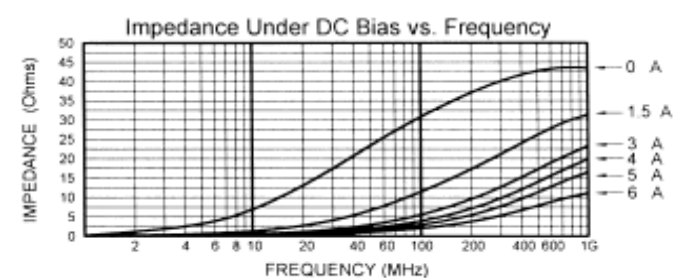
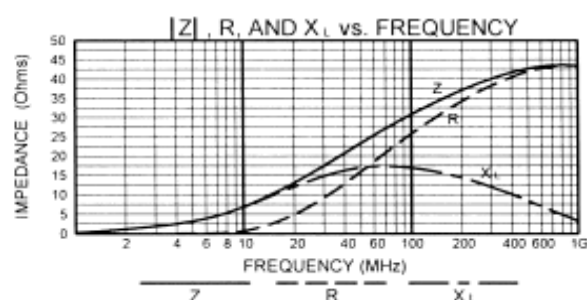
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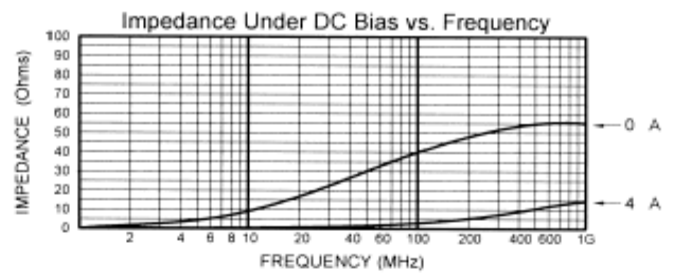
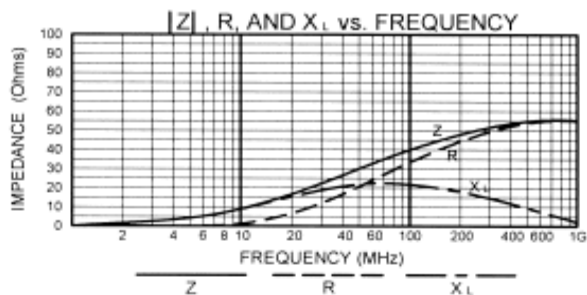
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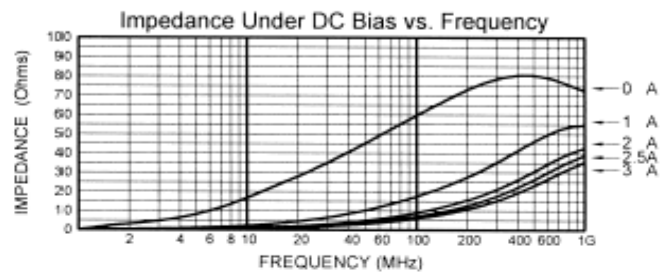
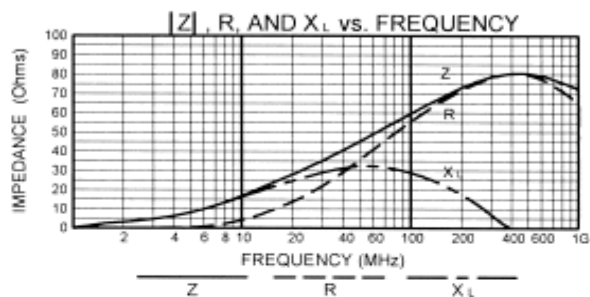
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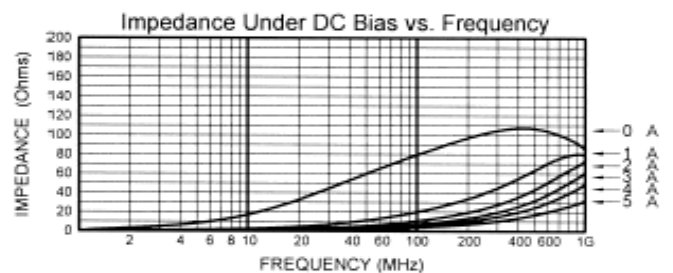
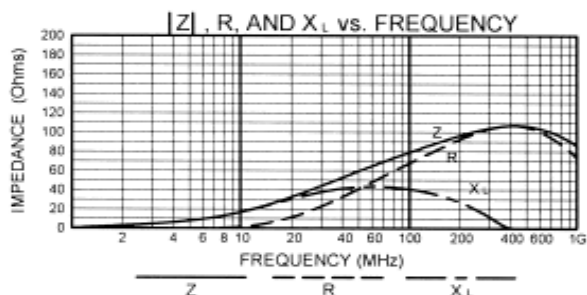
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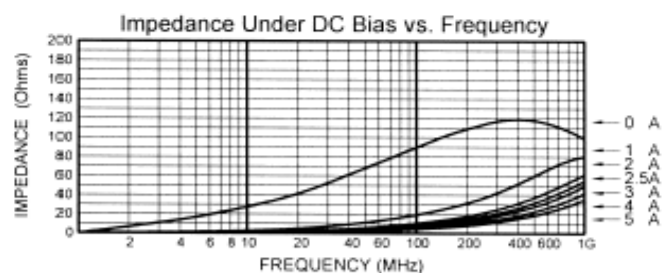
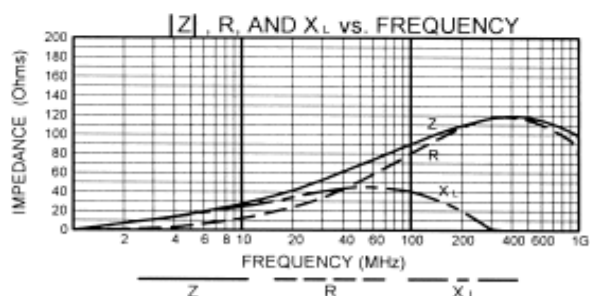
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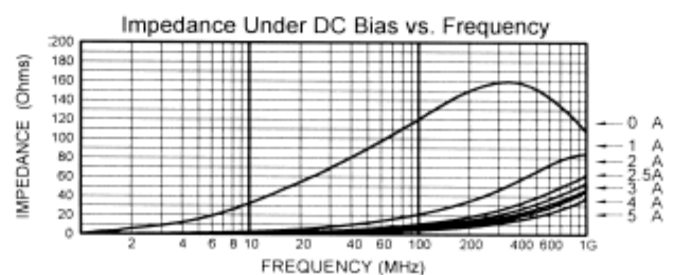
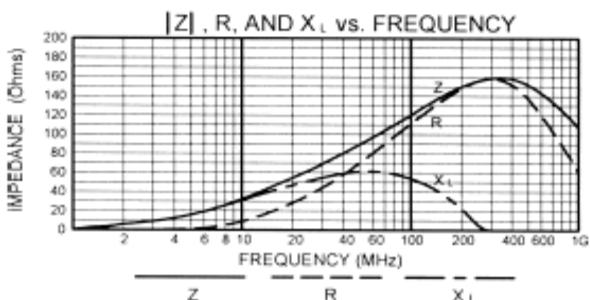
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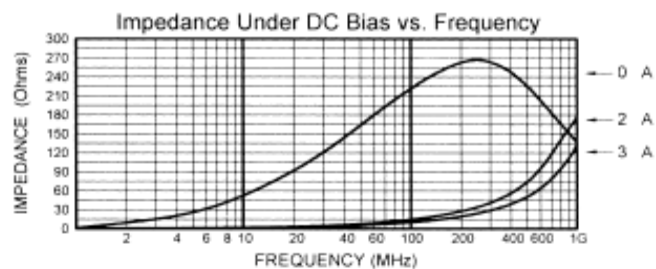
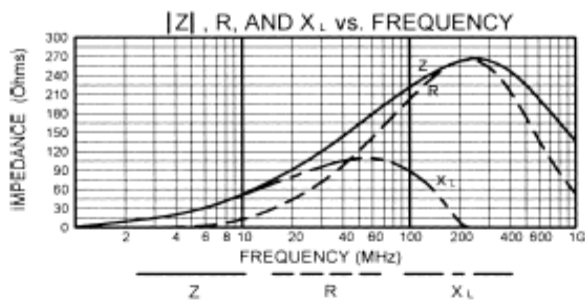
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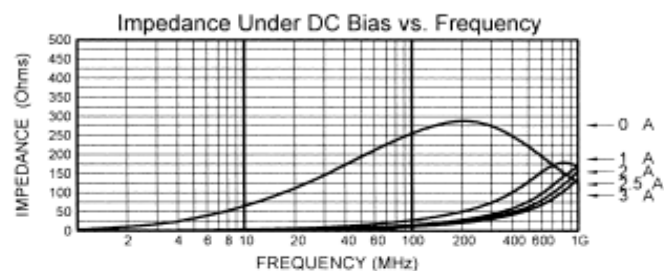
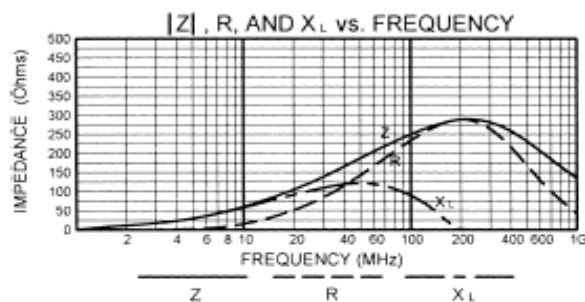
MHC2012S121U



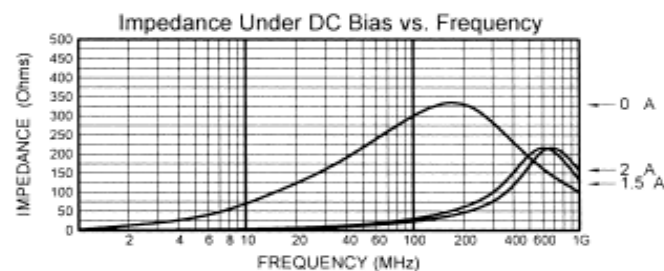
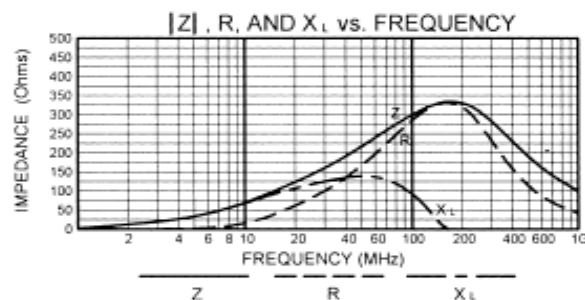
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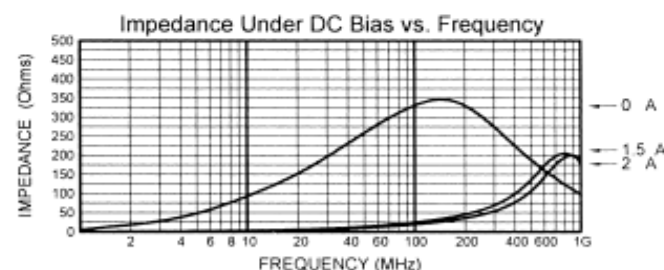
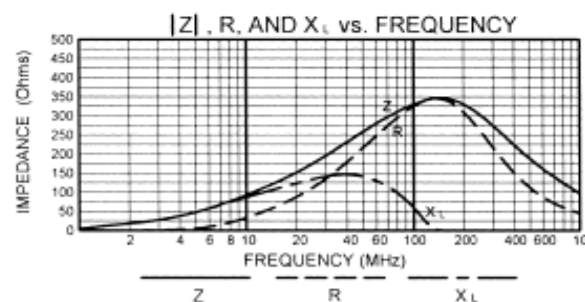
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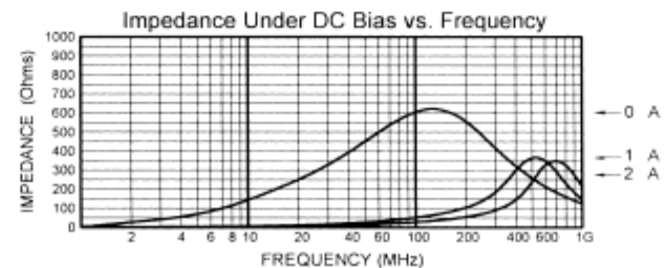
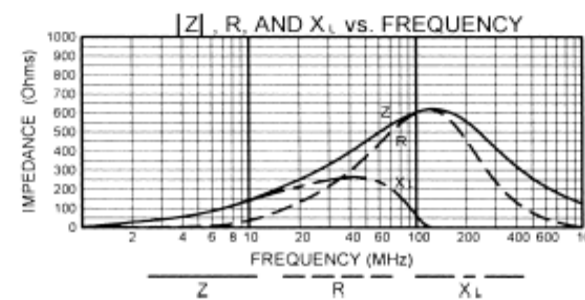
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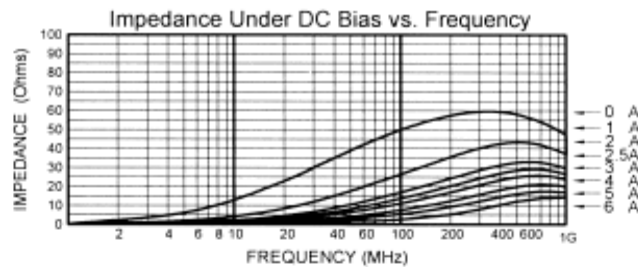
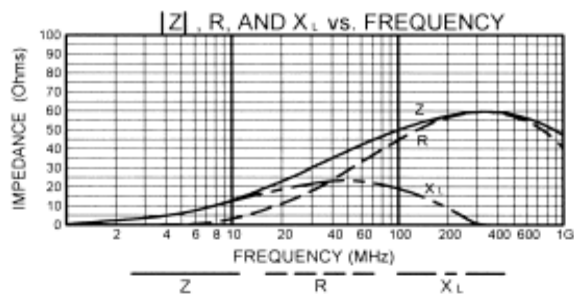
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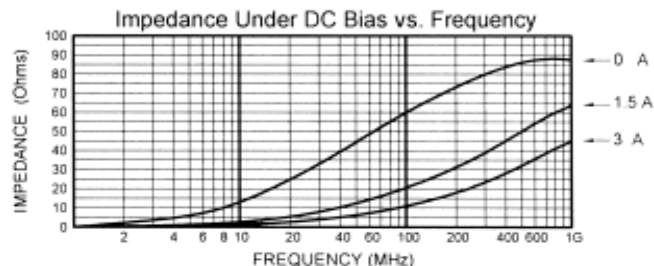
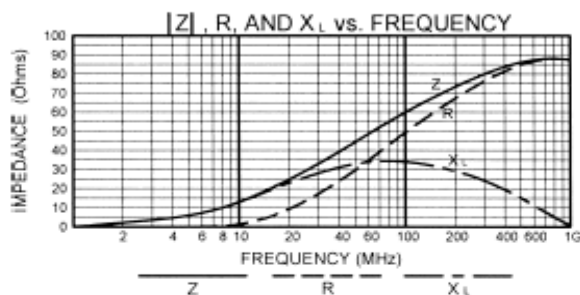
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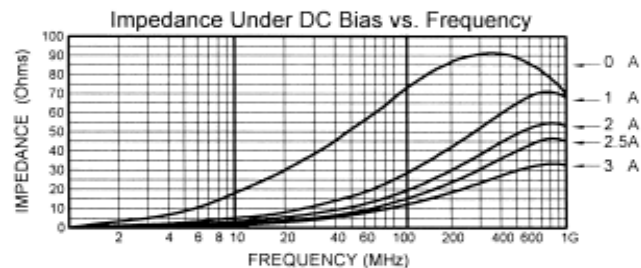
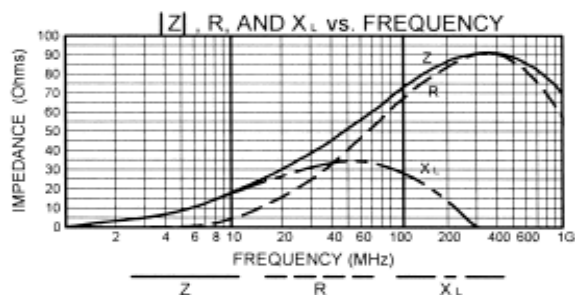
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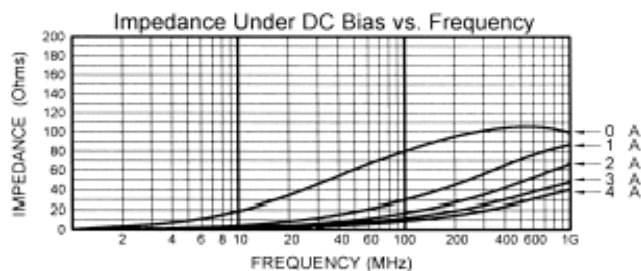
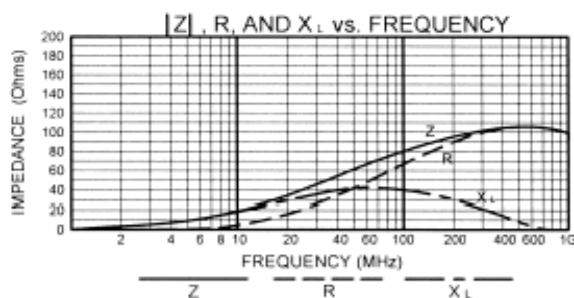
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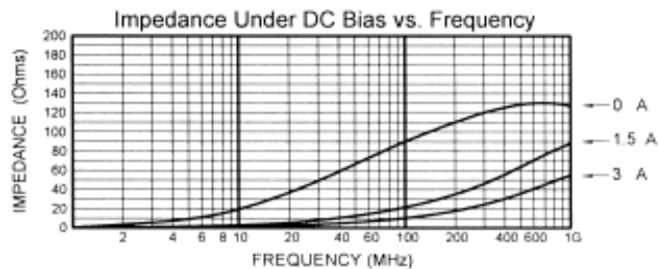
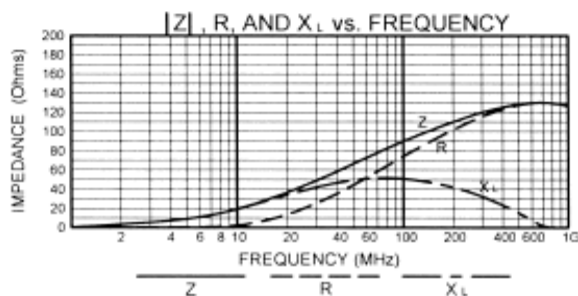
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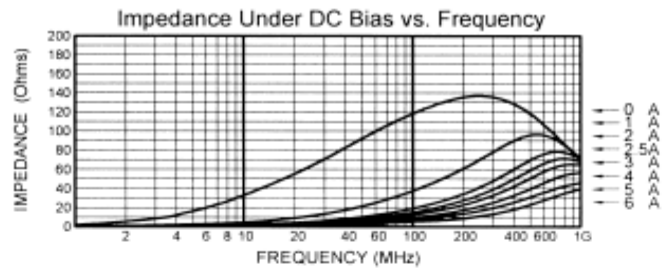
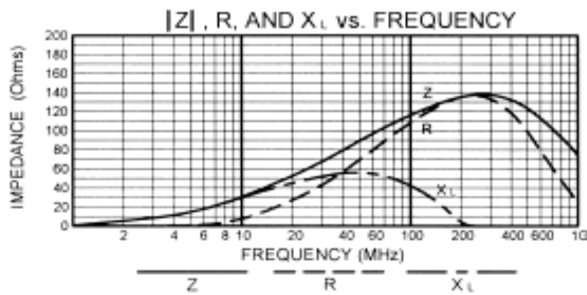
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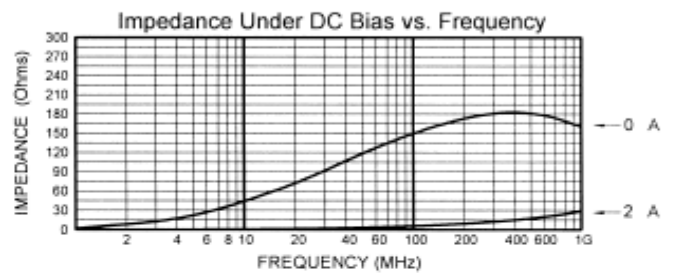
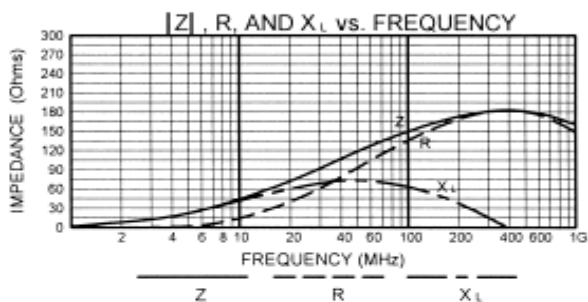
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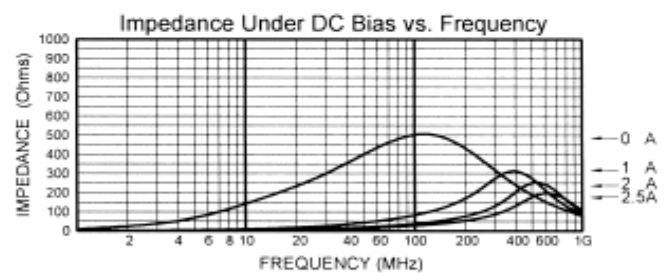
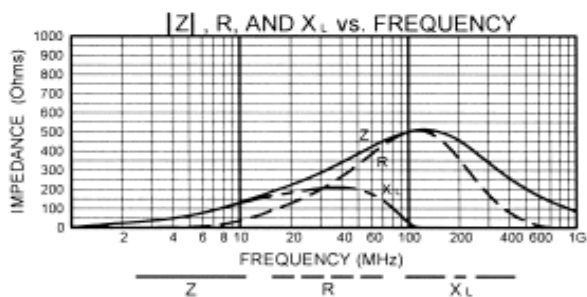
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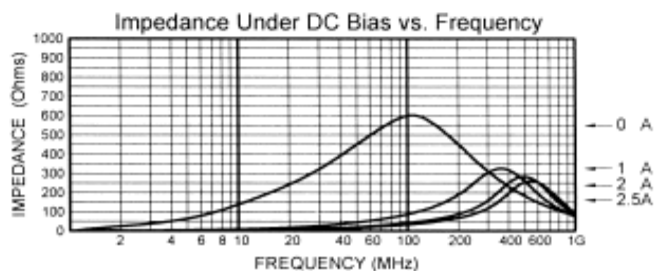
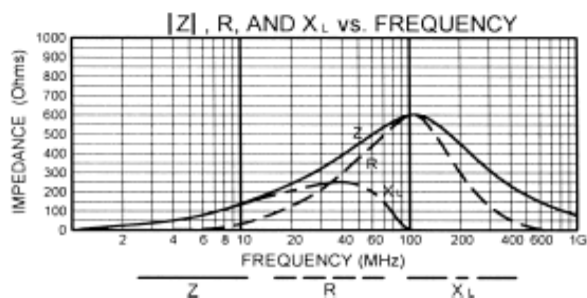
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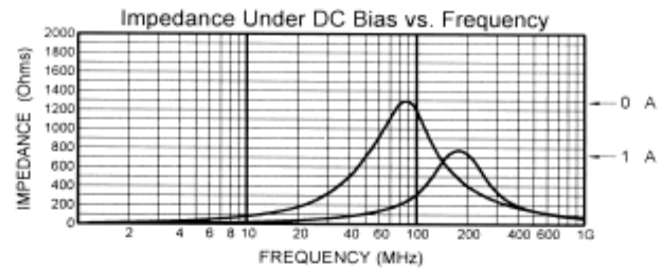
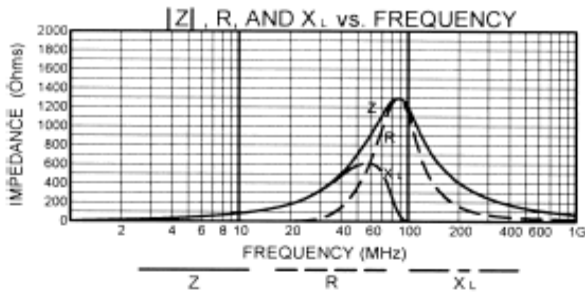
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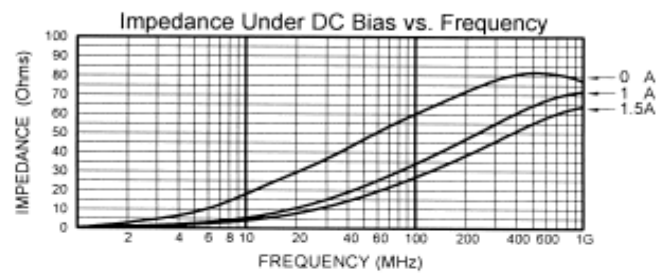
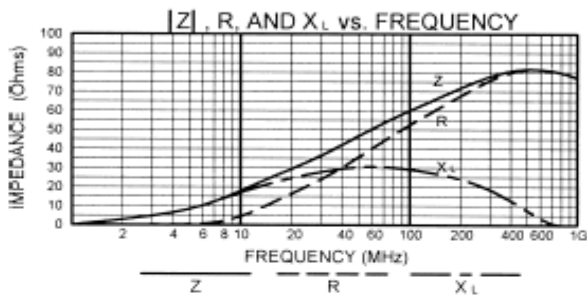
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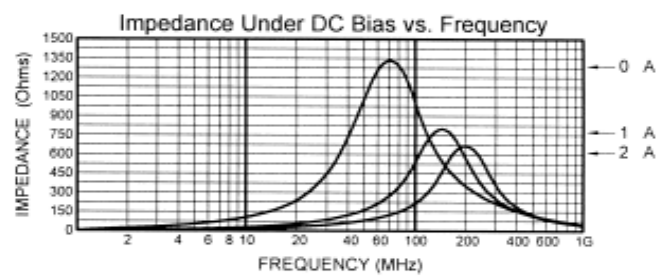
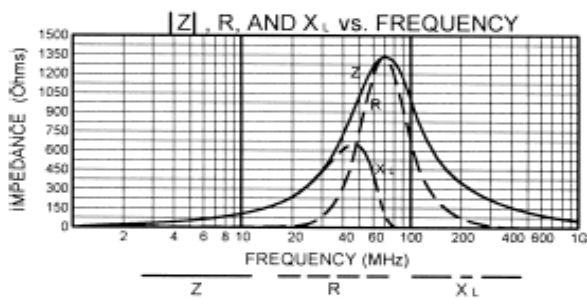
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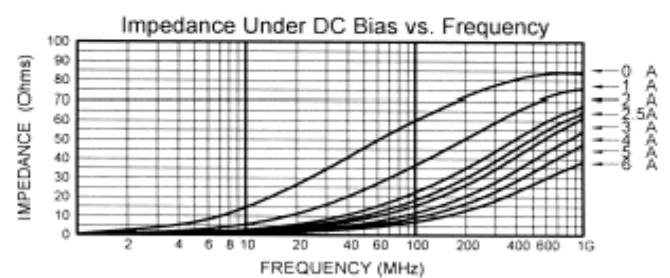
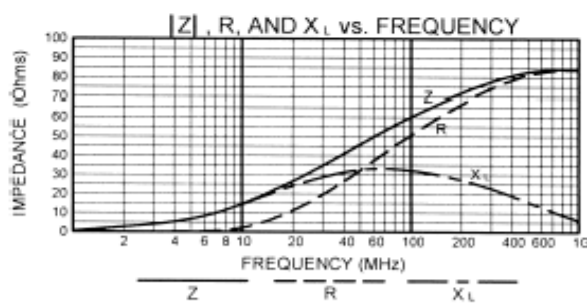
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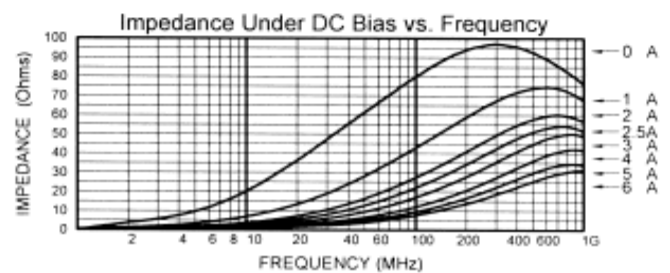
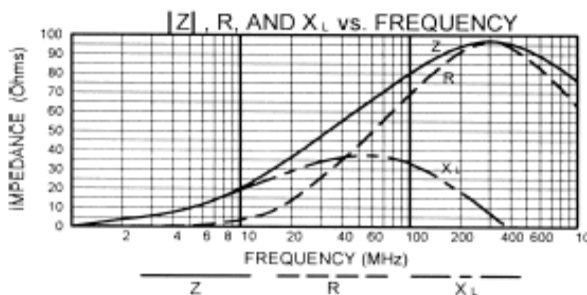
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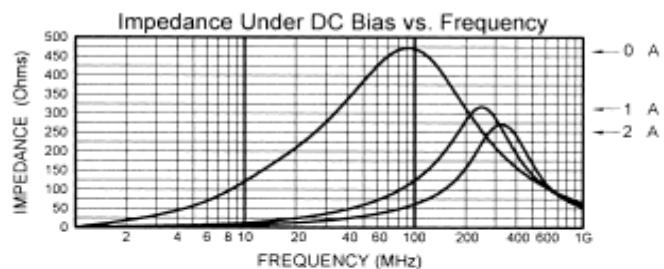
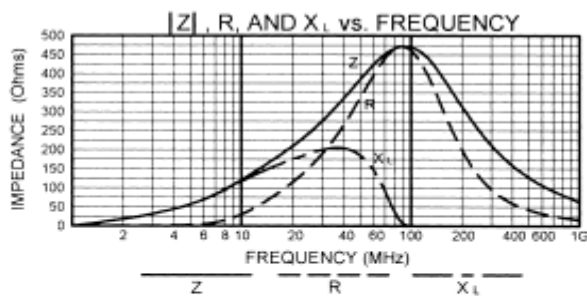
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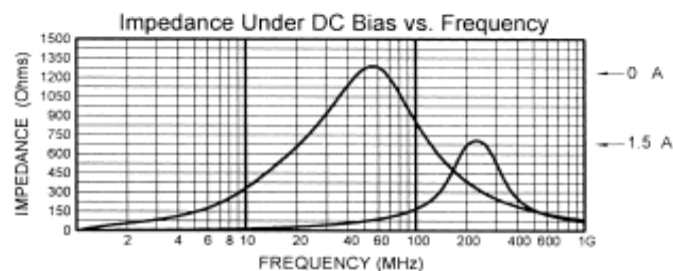
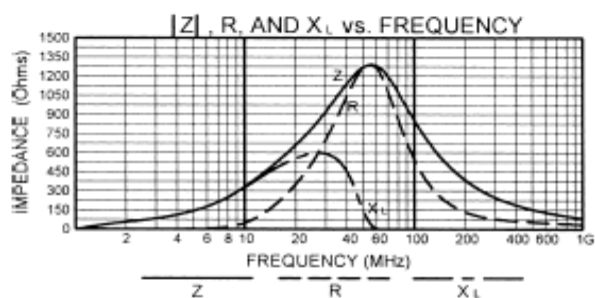
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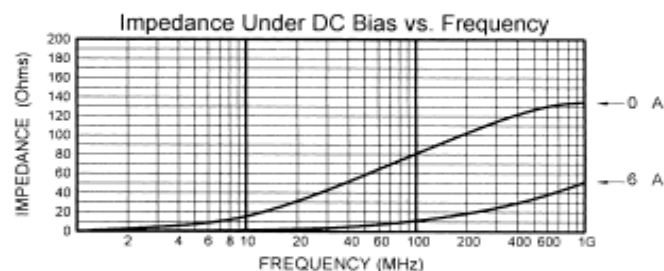
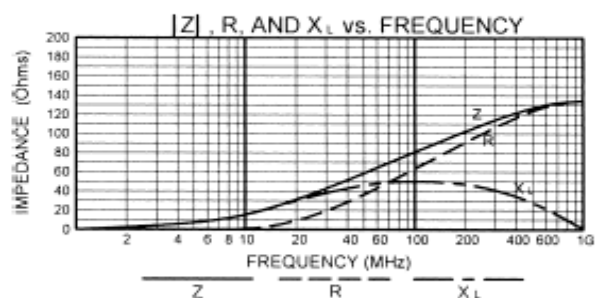
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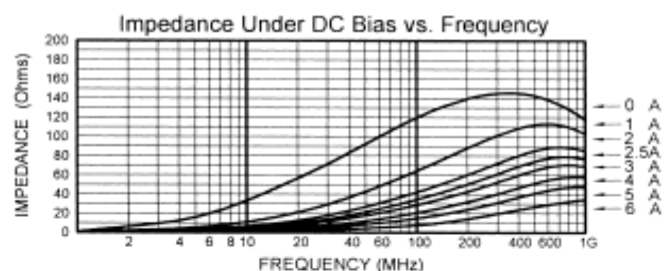
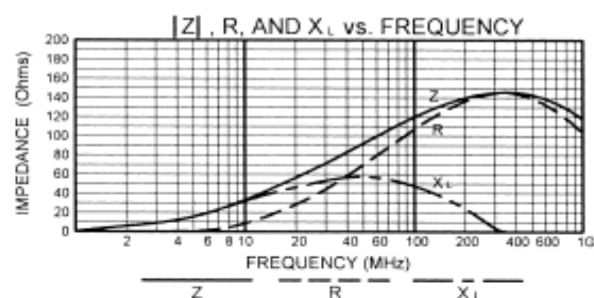
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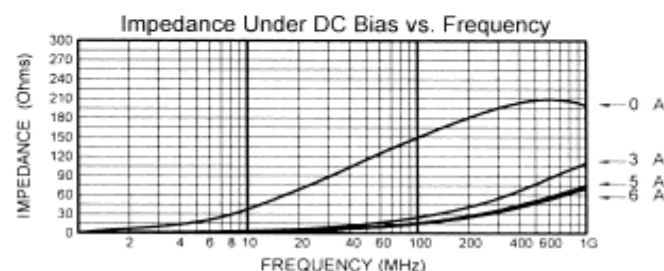
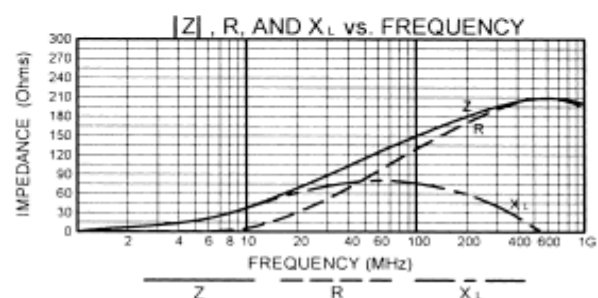
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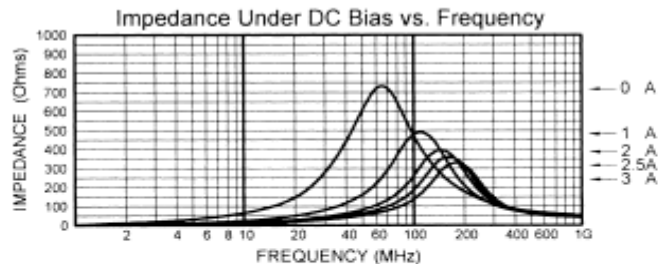
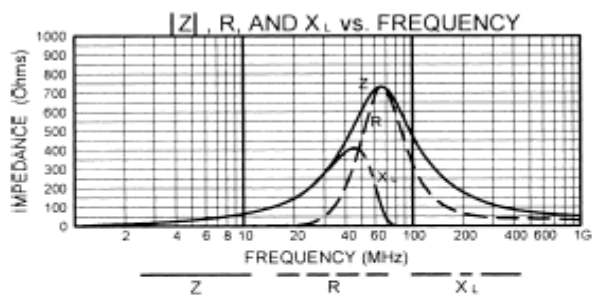
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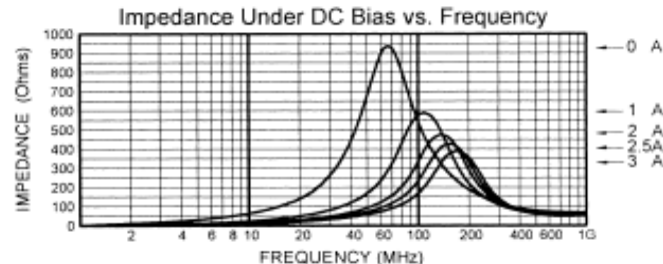
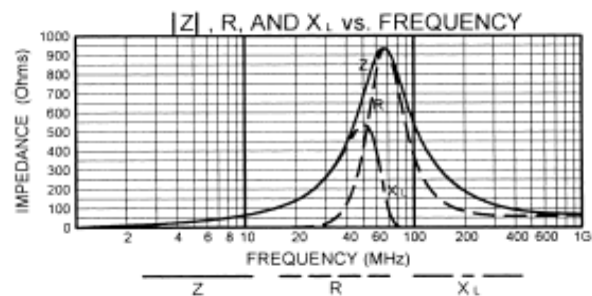
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MHC4532S601Q



MHC4532S681Q



MHC4532S132Q

